



## 1 Product Overview

BT3L is an embedded Bluetooth low energy (BLE) module that Tuya has developed. It consists of a highly integrated Bluetooth chip (TLSR8250F512ET32) and several peripheral components, with an embedded Bluetooth network protocol stack and robust library functions. BT3L also contains a low-power 32-bit multipoint control unit (MCU), BLE 5.0 component, 2.4 GHz radio component, 4 MB flash memory, 48 KB static random-access memory (SRAM), and nine multiplexing I/O interfaces.

### 1.1 Features

- ✧ Embedded low-power 32-bit MCU, which can also function as an application processor
  - Dominant frequency: 48 MHz
- ✧ Working voltage: 1.8 V to 3.6 V (Under 1.8 V to 2.7 V, the module can start but the RF performance is not guaranteed. Under 2.8 V to 3.6 V, the module performance is normal.)
- ✧ Peripherals: nine pulse width modulation (PWM) interfaces
- ✧ BLE RF features
  - Compatible with BLE 5.0
  - Up to 2 Mbit/s RF data rate
  - TX power: +10 dBm
  - RX sensitivity: -94.5 dBm at BLE 1 Mbit/s
  - Embedded advanced encryption standard (AES) hardware encryption
  - Onboard PCB antenna with 2.5 dBi gain

- Working temperature:  $-20^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$

## **1.2 Applications**

- ✧ Smart LED lights
- ✧ Smart households
- ✧ Smart low-power sensors

## Change History

No.	Date	Change Description	Version After Change
1	2019-03-09	This is the first release.	1.0.0
2	2019-07-23	1. Optimized the pin definition. 2. Standardized the dimensional tolerances. 3. Updated the temperature range, oven temperature, and working voltage settings. 4. Added packing methods.	2.0.0

## Contents

1 Product Overview .....	1
1.1 Features .....	1
1.2 Applications .....	2
Change History .....	3
2 Module Interfaces .....	6
2.1 Dimensions and Footprint .....	6
2.2 Interface Pin Definition .....	7
3 Electrical Parameters .....	9
3.1 Absolute Electrical Parameters .....	9
3.2 Electrical Conditions .....	9
3.3 Working Current .....	10
4 RF Features.....	11
4.1 Basic RF Features.....	11
4.2 RF Output Power.....	11
4.3 RF RX Sensitivity .....	12
5 Antenna Information .....	12
5.1 Antenna Type .....	12
5.2 Antenna Interference Reduction.....	12
6 Packaging Information and Production Instructions.....	13
6.1 Mechanical Dimensions .....	13
6.2 Production Instructions.....	14
6.3 Recommended Oven Temperature Curve .....	15
6.4 Storage Conditions.....	17
7 MOQ and Packing Information .....	18
8 Appendix: Statement .....	18

## Figures

Figure 2-1 BT3L pins .....	6
Figure 6-1 BT3L mechanical dimensions .....	13
Figure 6-2 HIC for BT3L .....	14
Figure 6-3 Oven temperature curve .....	16

## Tables

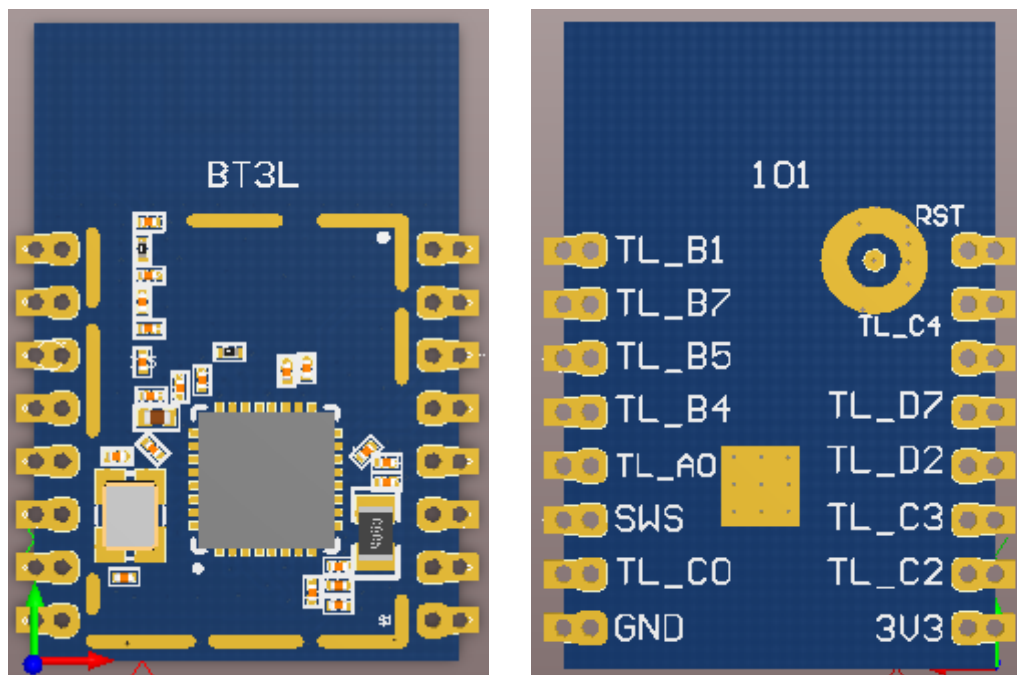
Table 2-1 BT3L interface pins .....	7
Table 3-1 Absolute electrical parameters .....	9
Table 3-2 Normal electrical conditions .....	9
Table 3-3 Current during constant transmission and receiving .....	10
Table 4-1 Basic RF features .....	11
Table 4-2 Power during constant transmission .....	11
Table 4-3 RX sensitivity .....	12

## 2 Module Interfaces

### 2.1 Dimensions and Footprint

BT3L has two rows of pins with a 2 mm pin spacing.

The BT3L dimensions (H x W x D) are  $3.3 \pm 0.15$  mm x  $16 \pm 0.35$  mm x  $24 \pm 0.35$  mm. The PCB thickness is  $0.8 \pm 0.1$  mm. Figure 2-1 shows the BT3L pins.



**Figure 2-1 BT3L pins**

## 2.2 Interface Pin Definition

**Table 2-1 BT3L interface pins**

Pin No.	Symbol	I/O Type	Function
1	RST	I/O	Hardware reset pin, which is active at a low level and is connected to pin 25 on the IC
2	ADC	AI	12-bit ADC, which is connected to pin 24 on the IC
3	NC	I/O	NC
4	TL_D7	I/O	GPIO, which is connected to pin 2 on the IC
5	TL_D2	I/O	Common I/O, which can be used as a PWM output of the LED drive and is connected to pin 31 on the IC
6	TL_C3	I/O	Common I/O, which can be used as a PWM output of the LED drive and is connected to pin 23 on the IC
7	TL_C2	I/O	Common I/O, which can be used as a PWM output of the LED drive and is connected to pin 22 on the IC
8	VDD_BAT	P	Power supply pin (3.3 V)
9	GND	P	Power supply reference ground pin
10	TL_C0	I/O	GPIO, which is connected to pin 20 on the IC
11	SWS	Input	Programming pin, which is connected to pin 5 on the IC

Pin No.	Symbol	I/O Type	Function
12	TL_A0	I/O	GPIO, which is connected to pin 3 on the IC
13	TL_B4	I/O	Common I/O, which can be used as a PWM output of the LED drive and is connected to pin 14 on the IC
14	TL_B5	I/O	Common I/O, which can be used as a PWM output of the LED drive and is connected to pin 15 on the IC
15	TL_B7	I/O	Serial interface receiving pin (UART RX), which is connected to pin 17 on the IC
16	TL_B1	I/O	Serial interface transmission pin (UART TX), which is connected to pin 6 on the IC

Note:

1. **P** indicates power supply pins, **I/O** indicates input/output pins, and **AI** indicates analog input pins.
2. If you have special requirements for light colors controlled by PWM outputs, contact Tuya business personnel.



## 3 Electrical Parameters

### 3.1 Absolute Electrical Parameters

**Table 3-1 Absolute electrical parameters**

Parameter	Description	Minimum Value	Maximum Value	Unit
T <sub>s</sub>	Storage temperature	−65	150	°C
VCC	Power supply voltage	−0.3	3.9	V
Static electricity voltage (human body model)	T <sub>amb</sub> = 25°C	N/A	2	kV
Static electricity voltage (machine model)	T <sub>amb</sub> = 25°C	N/A	0.5	kV

### 3.2 Electrical Conditions

**Table 3-2 Normal electrical conditions**

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
T <sub>a</sub>	Working temperature	−20	N/A	85	°C
VCC	Working voltage	2.8	3.3	3.6	V
V <sub>IH</sub>	I/O high-	VCC x 0.7	N/A	VCC	V

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
	level input				
$V_{OL}$	I/O low-level output	VSS	N/A	$VCC \times 0.1$	V
$V_{OH}$	I/O high-level output	$VCC \times 0.9$	N/A	VCC	V

### 3.3 Working Current

**Table 3-3 Current during constant transmission and receiving**

Symbol	Description	Typical Value	Unit
$I_{tx}$	Constant transmission, 0 dBm output power	6.7	mA
$I_{rx}$	Constant receiving	6.3	mA
$I_{DC}$	Connected to a mesh network	7.4	mA
$I_{deepsleep1}$	Deep sleep mode 1 (16 KB RAM is reserved.)	1.2	$\mu A$
$I_{deepsleep2}$	Deep sleep mode 2 (No RAM is reserved.)	0.4	$\mu A$

## 4 RF Features

### 4.1 Basic RF Features

**Table 4-1 Basic RF features**

Parameter	Description
Frequency band	2.4 GHz ISM band
Wireless standard	BLE 5.0
Data transmission rate	1 Mbit/s or 2 Mbit/s
Antenna type	Onboard PCB antenna

### 4.2 RF Output Power

**Table 4-2 Power during constant transmission**

Parameter	Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power	-22	10	10.5	dBm
20 dB modulation signal bandwidth (1 Mbit/s)	N/A	2500	N/A	kHz
20 dB modulation signal bandwidth (2 Mbit/s)	N/A	1400	N/A	kHz

## 4.3 RF RX Sensitivity

**Table 4-3 RX sensitivity**

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
RX sensitivity	1 Mbit/s	N/A	-94.5	N/A	dBm
	2 Mbit/s	N/A	-91	N/A	
Frequency offset	1 Mbit/s	-250	N/A	+300	kHz
	2 Mbit/s	-300	N/A	+200	
Co-channel interference suppression	N/A	N/A	-10	N/A	dB

## 5 Antenna Information

### 5.1 Antenna Type

BT3L uses an onboard PCB antenna.

### 5.2 Antenna Interference Reduction

To ensure optimal RF performance, it is recommended that the antenna be at least 15 mm away from other metal parts. If metal materials are wrapped around the antenna, the wireless signals will be reduced greatly, deteriorating the RF performance. Because BT3L is inserted to the PCB, sufficient space needs to be reserved for the antenna.

## 6 Packaging Information and Production Instructions

### 6.1 Mechanical Dimensions

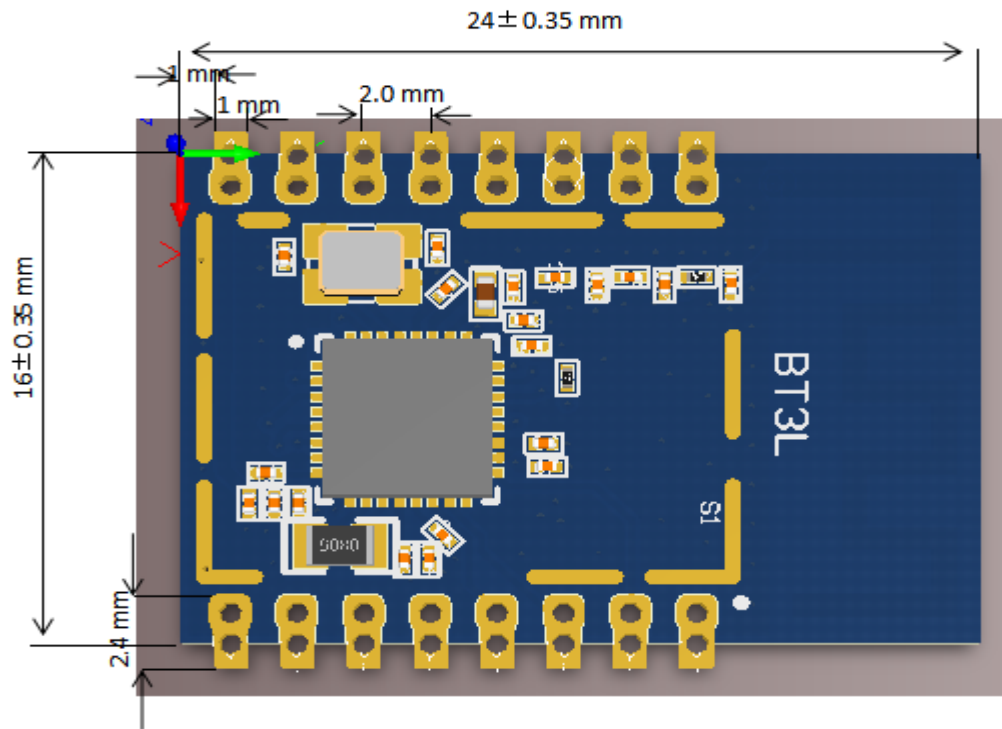


Figure 6-1 BT3L mechanical dimensions

Note:

The default dimensional tolerance is  $\pm 0.35$  mm, and the tolerance for some measurements is  $\pm 0.1$  mm. If a customer has other requirements, clearly specify them in the datasheet after communication.

## 6.2 Production Instructions

1. Use an SMT placement machine to mount components to the stamp hole module that Tuya produces within 24 hours after the module is unpacked and the firmware is burned. If not, vacuum pack the module again. Bake the module before mounting components to the module.

- (1) SMT placement equipment

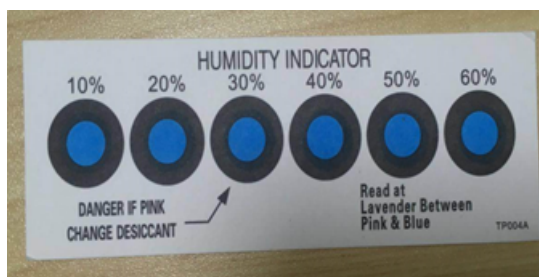
- i. Reflow soldering machine
- ii. Automated optical inspection (AOI) equipment
- iii. Nozzle with a 6 mm to 8 mm diameter

- (2) Baking equipment

- i. Cabinet oven
- ii. Anti-static heat-resistant trays
- iii. Anti-static heat-resistant gloves

2. Storage conditions for a delivered module are as follows:

- (1) The moisture-proof bag is placed in an environment where the temperature is below 30°C and the relative humidity is lower than 70%.
- (2) The shelf life of a dry-packaged product is six months from the date when the product is packaged and sealed.
- (3) The package contains a humidity indicator card (HIC).



**Figure 6-2 HIC for BT3L**

3. Bake a module based on HIC status as follows when you unpack the module package:
  - (1) If the 30%, 40%, and 50% circles are blue, bake the module for 2 consecutive hours.
  - (2) If the 30% circle is pink, bake the module for 4 consecutive hours.
  - (3) If the 30% and 40% circles are pink, bake the module for 6 consecutive hours.
  - (4) If the 30%, 40%, and 50% circles are pink, bake the module for 12 consecutive hours.
4. Baking settings:
  - (1) Baking temperature:  $125\pm5^{\circ}\text{C}$
  - (2) Alarm temperature:  $130^{\circ}\text{C}$
  - (3) SMT placement ready temperature after natural cooling:  $< 36^{\circ}\text{C}$
  - (4) Number of drying times: 1
  - (5) Rebaking condition: The module is not soldered within 12 hours after baking.
5. Do not use SMT to process modules that have unpacked for over three months. Electroless nickel immersion gold (ENIG) is used for the PCBs. If the solder pads are exposed to the air for over three months, they will be oxidized severely and dry joints or solder skips may occur. Tuya is not liable for such problems and consequences.
6. Before SMT placement, take electrostatic discharge (ESD) protective measures.
7. To reduce the reflow defect rate, draw 10% of the products for visual inspection and AOI before first SMT placement to determine a proper oven temperature and component placement method. Draw 5 to 10 modules every hour from subsequent batches for visual inspection and AOI.

### **6.3 Recommended Oven Temperature Curve**

Perform SMT placement based on the following reflow oven temperature curve. The highest temperature is  $245^{\circ}\text{C}$ .

Based on the IPC/JEDEC standard, perform reflow soldering on a module at most twice.

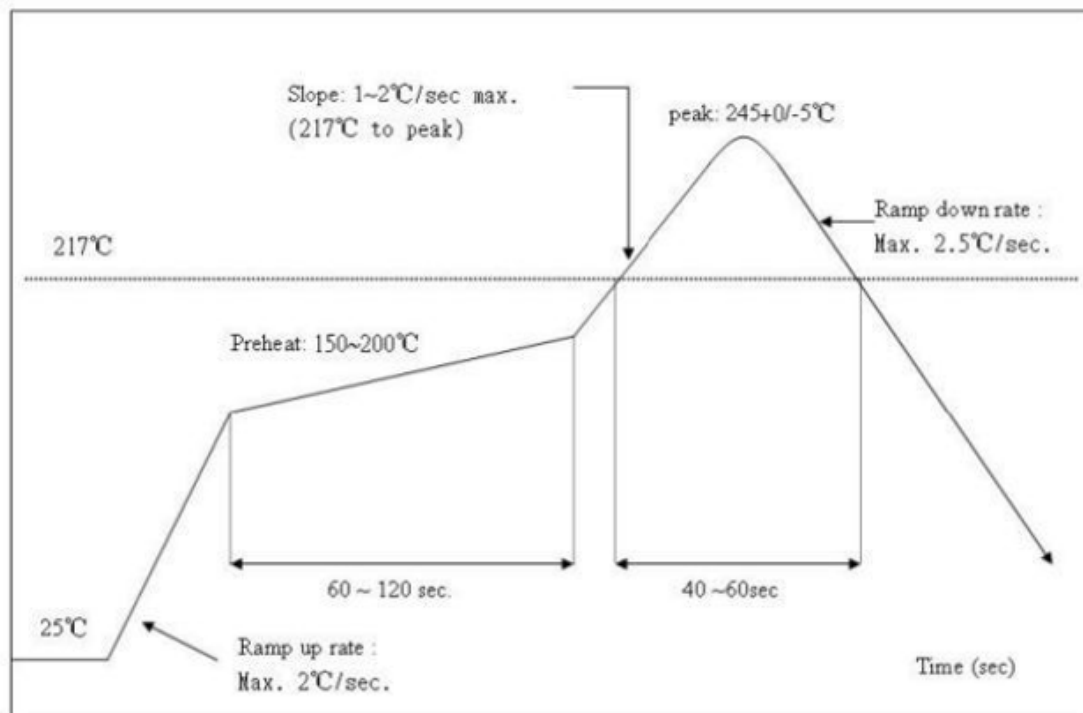


Figure 6-3 Oven temperature curve



## 6.4 Storage Conditions

	<b>CAUTION</b> <b>This bag contains</b> <b>MOISTURE-SENSITIVE DEVICES</b>	<b>LEVEL</b> <div style="border: 1px solid black; padding: 5px; display: inline-block;"> <b>3</b> </div>
If Blank, see adjacent bar code label		
1. Calculated shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)		
2. Peak package body temperature: <u>260</u> $^{\circ}\text{C}$ <small>If Blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must		
a) Mounted within: <u>168</u> hrs. of factory conditions <small>If Blank, see adjacent bar code label</small>		
≤ $30^{\circ}\text{C}/60\%\text{RH}$ , OR		
b) Stored at $<10\%\text{RH}$		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card is $> 10\%$ when read at $23 \pm 5^{\circ}\text{C}$		
b) 3a or 3b not met.		
5. If baking is required, devices may be baked for 48 hrs. at $125 \pm 5^{\circ}\text{C}$		
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ <small>If Blank, see adjacent bar code label</small>		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

## 7 MOQ and Packing Information

MOQ and Packing Information				
Product Model	MOQ (PCS)	Packing Method	Number of Modules in Each Reel Pack	Number of Reel Packs in Each Box
BT3L	3600	Carrier tape and reel packing	900	4

## 8 Appendix: Statement

### Federal Communications Commission (FCC) Declaration of Conformity

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules.

Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located or operating in conjunction with any other antenna or transmitter.

15.105 Information to the user.

(b) For a Class B digital device or peripheral, the instructions furnished the user shall include the following or similar statement, placed in a prominent location in the text of the manual:

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules.

These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause

harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator and your body.

### Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

The availability of some specific channels and/or operational frequency bands is country dependent and firmware programmed at the factory to match the intended destination.

The firmware setting is not accessible by the end user.

The final end product must be labeled in a visible area with the following:

"Contains Transmitter Module 2ANDL-BT3L"

This radio module must not be installed to co-locate and operating simultaneously with other radios in host system, additional testing and equipment authorization may be required to operating simultaneously with other radio.

## Declaration of Conformity European notice



Hereby, Hangzhou Tuya Information Technology Co., Ltd. declares that this Wi-Fi module product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EC. A copy of the Declaration of conformity can be found at <https://www.tuya.com>.

EN 300 328 V2.1.1

EN 301 489-1 V2.1.1; EN 301 489-17 V3.1.1

EN 62311:2008

EN 60950-1:2006+A11:2009+A1:2010+A12:2011+A2:2013